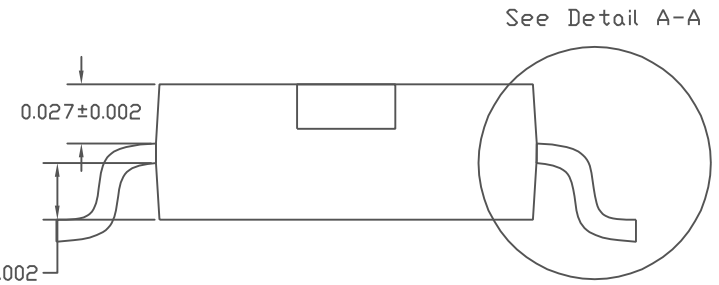
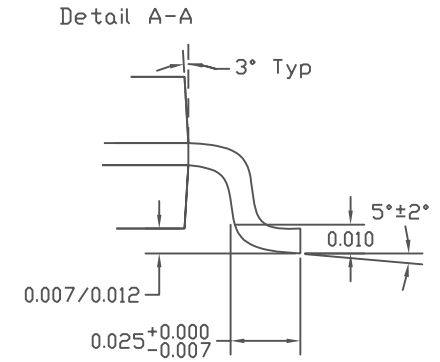


ECN	REV.	DESCRIPTION	DATE	APP'D:
10018	-	INITIAL RELEASE	02/21/01	BF



NOTES:
 BODY : PLASTIC, SEMICONDUCTOR GRADE
 LEAD FRAME : COPPER, OLIN 194
 LEAD FINISH : 50μIN Au, OVER 50μIN NI
 FRAME THICKNESS : 0.008" +/- 0.001"



TITLE: 16 Lead SOIC Open-Pak (0.150" Wide)

MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: S.D.
GEN. TOL.: ±0.005	DATE: 11/28/00	APP'D: BF 2/21/01
SSM P/N: PS0161501	DWG. NO.: SOIC16-OP-01	REV.: -